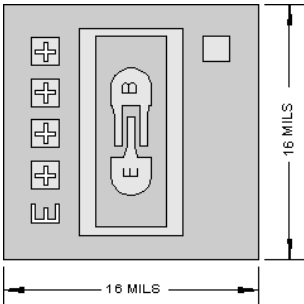




Data Sheet No. 2C3960

Chip Type 2C3960
 Geometry 0003
 Polarity NPN

Generic Packaged Part:
 2N3960



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Chip type **2C3960** by Semicoa Semi-conductors provides performance similar to these devices.

Part Numbers:

2N3960, 2N3960UB, SD3960F, SQ3960, SQ3960F

Product Summary:

APPLICATIONS:

Designed for high-speed current-mode logic switching.

Features:

Mechanical Specifications		
Metallization	Top	Al - 15 kÅ min.
	Backside	Au - 6.5 kÅ nom.
Bonding Pad Size	Emitter	2.7 mils x 2.7 mils
	Base	2.7 mils x 2.7 mils
Die Thickness	8 mils nominal	
Chip Area	16 mils x 16 mils	
Top Surface	Silox Passivated	

Electrical Characteristics				
T _A = 25°C				
Parameter	Test conditions	Min	Max	Unit
BV _{CEO}	I _C = 10.0 mA	12	---	V dc
BV _{CBO}	I _C = 10 µA	20	---	V dc
BV _{EBO}	I _E = 10.0 mA	4.5	---	V dc
I _{CEX}	V _{CE} = 10 V, V _{EB} = 2.0 V	---	5.0	nA
h _{FE1}	I _C = 1.0 mA dc, V _{CE} = 1.0 V	25	---	---
h _{FE2}	I _C = 10 mA dc, V _{CE} = 1.0 V	40	400	---
h _{FE3}	I _C = 30 mA dc, V _{CE} = 1.0 V	25	---	---
V _{CE(sat)}	I _C = 30 mA dc, I _B = 3.0 mA	---	0.3	V dc

Due to limitations of probe testing, only dc parameters are tested. This must be done with pulse width less than 300 µs, duty cycle less than 2%.

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